Preliminary



Steep Roll-off Filter for 869.00 MHz Unlicensed Band

• Complies with Directive 2002/95/EC (RoHS)

• No Matching Required for Operation in 50 Ω Environment

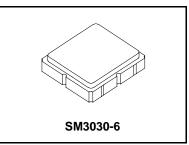


Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	14	dBm
DC Voltage on any Non-ground Terminal	5	V
Operating Temperature Range	-30 to +65	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 Cycles/10 seconds Maximum	265	°C

SF2137E-1

869.00 MHz **SAW Filter**



Electrical Characteristics

Characteristic	Sym	Notes	Min	Тур	Max	Units
Center Frequency	f _C			869.00		MHz
Insertion Loss, 868 to 870 MHz	IL			2.7	3.5	dB
Amplitude Ripple, 868 to 870 MHz				0.2	0.7	dB _{P-P}
Attenuation Referenced to 0 dB:						
DC to 828 MHz			45	51		
828 to 849 MHz			30	40		1
881 to 890 MHz			22	35		dB
890 to 925 MHz			22	38		ub ub
925 to 1200 MHz			40	49		
1200 to 1740 MHz			36	49		
Source Impedance	Z _S			50		Ω
Load Impedance	Z _L			50		Ω

Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint	
Lid Symbolization, Y=year, WW=week, S=shift, Dot=pin 1 indicator	994, YWWS	
Standard Reel Quantity Reel Size 7 Inch	500 Pieces/Reel	
Reel Size 13 Inch	3000 Pieces/Reel	

Electrical Connections

Connection	Terminals
Port 1	2
Port 2	5
Case Ground	All others

CAUTION: Electrostatic Sensitive Device. Observe precautions for handling. Notes:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.

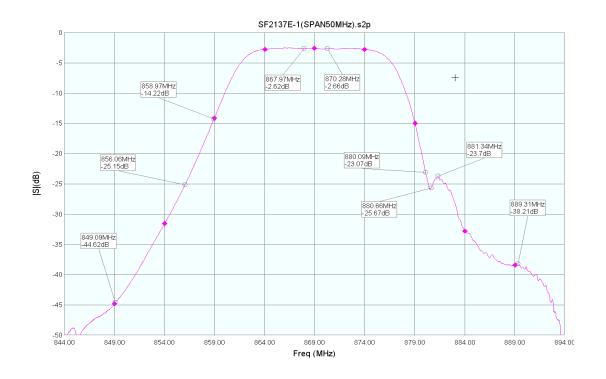
Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.

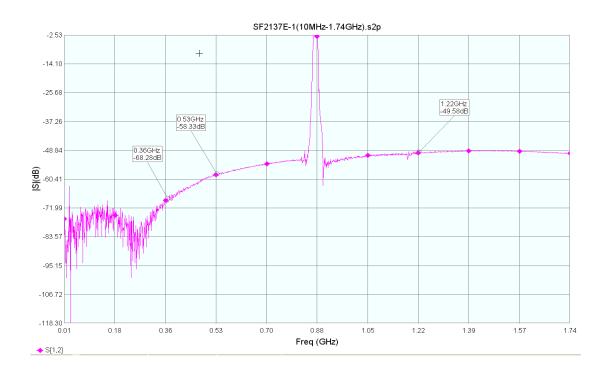
Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.

The design, manufacturing process, and specifications of this filter are subject to change.

- US and international patents may apply.

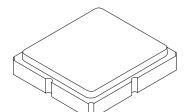
 RFM, stylized RFM logo, and RF Monolithics, Inc. are registered trademarks of RF Monolithics, Inc.

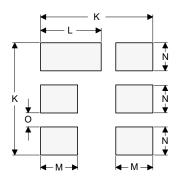




SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint





PCB Footprint Top View

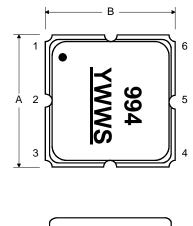
Case and PCB Footprint Dimensions

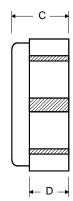
Dimension		mm			Inches	
Dimension	Min	Nom	Max	Min	Nom	Max
Α	2.87	3.00	3.13	0.113	0.118	0.123
В	2.87	3.00	3.13	0.113	0.118	0.123
С	1.12	1.25	1.40	0.044	0.049	0.055
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
Н	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
М		1.05			0.041	
N		0.81			0.032	
0		0.38			0.015	

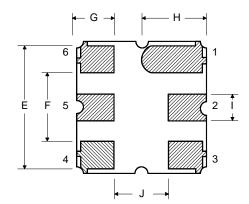
Case Materials

Materials			
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel		
Lid Plating	2.0 to 3.0 µm Nickel		
Body	Al ₂ O ₃ Ceramic		
Pb Free			

Top View

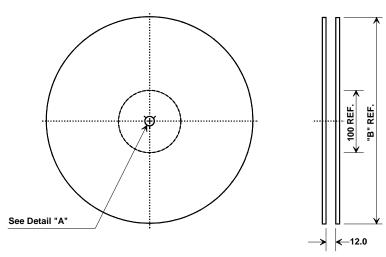




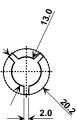


Bottom View

Tape and Reel Specifications

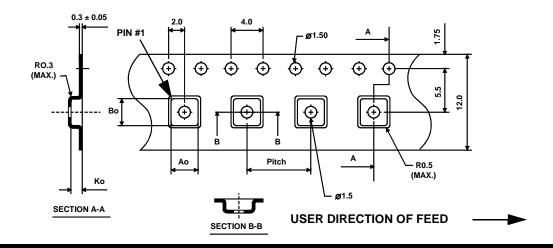


	"B"	Quantity Per Reel
Inches	millimeters	Qualitity i el iteel
7	178	500
13	330	3000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Во	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm



Typical Solder Reflow Profile

